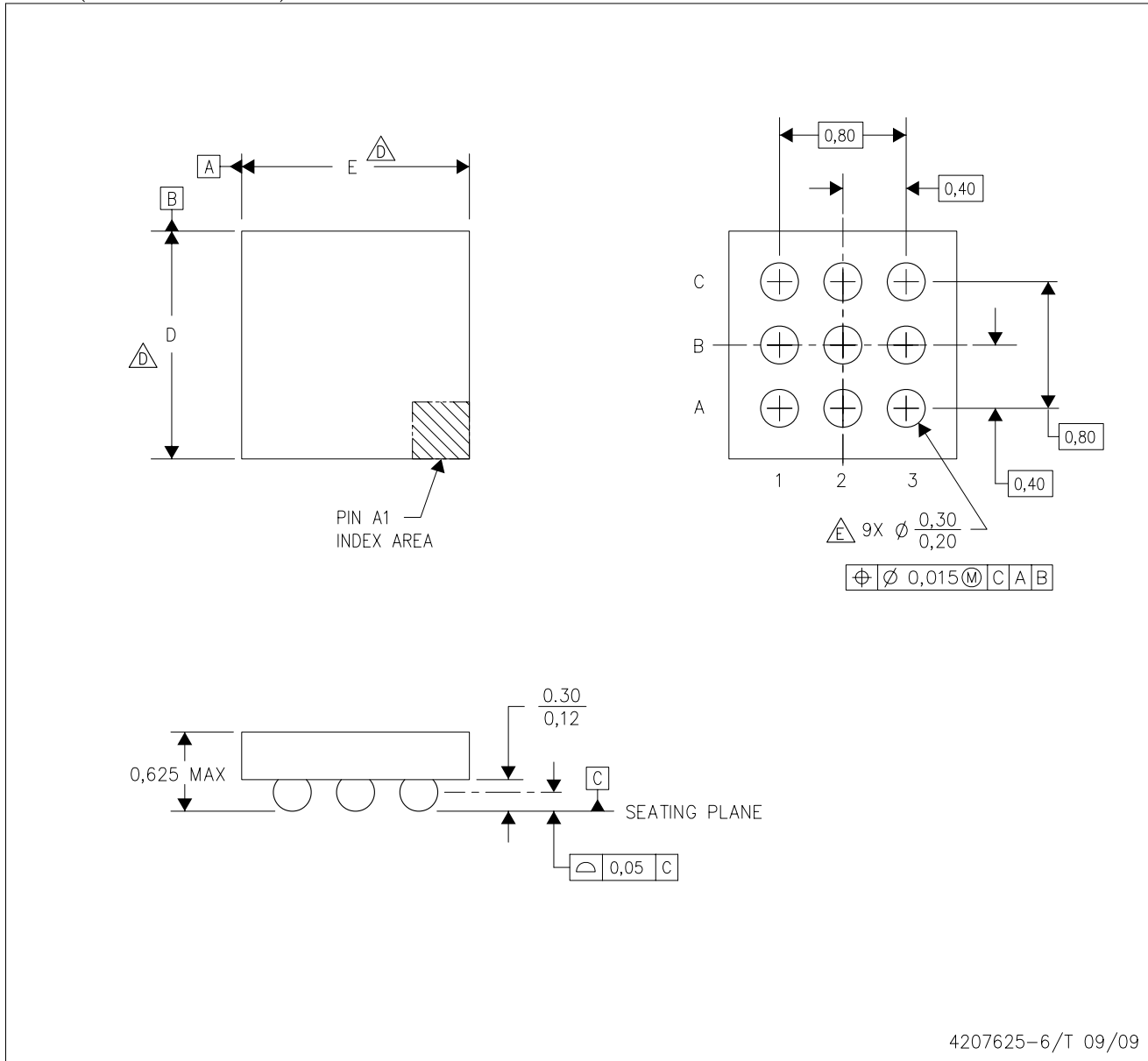


YFF (S-XBGA-N9)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - \triangle Devices in YFF package can have dimensions D ranging from 1.16 to 1.85 mm and dimension E ranging from 1.16 to 1.85 mm. To determine the exact package size of a particular device, refer to the device datasheet or contact a local TI representative.
 - E. Reference Product Data Sheet for array population.
3 x 3 matrix pattern is shown for illustration only.
 - F. This package contains Pb-free balls.

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